

Process Control and Enhancement

by

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Professor

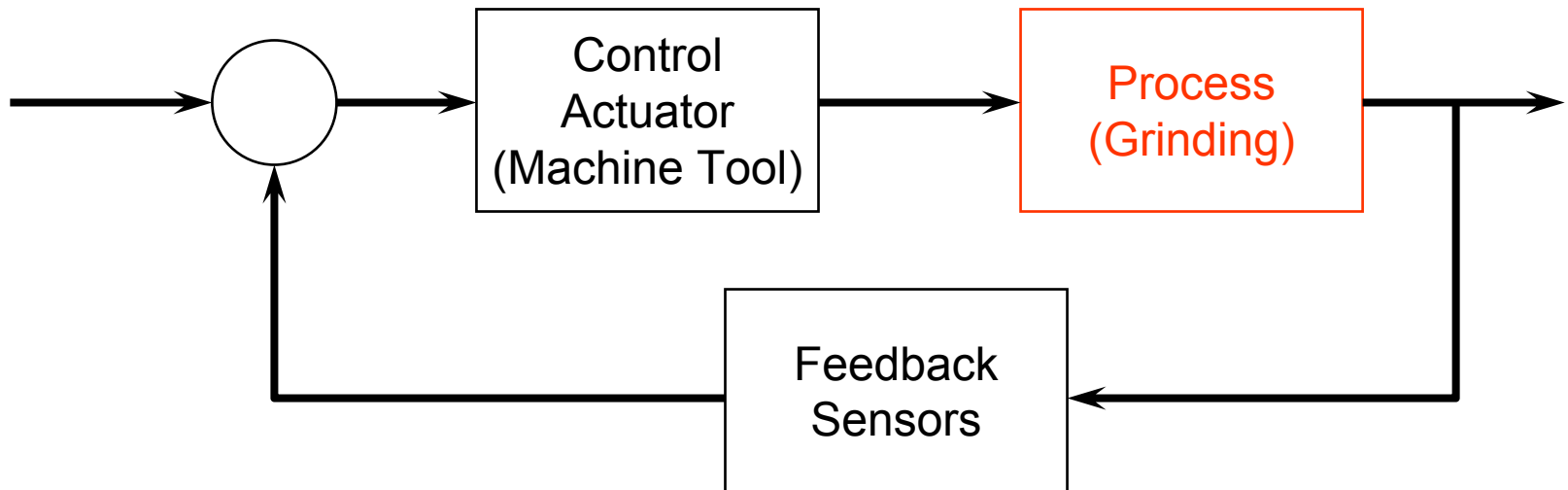
**The George W. Woodruff School of Mechanical Engineering
and the**

Manufacturing Research Center

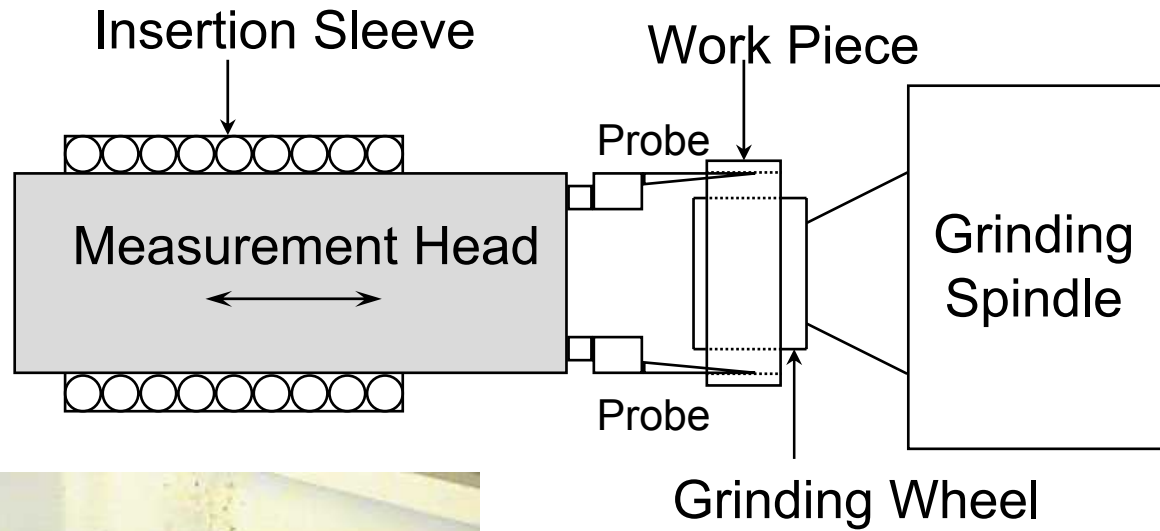
Georgia Institute of Technology

Atlanta, GA 30332-0405

Manufacturing Process

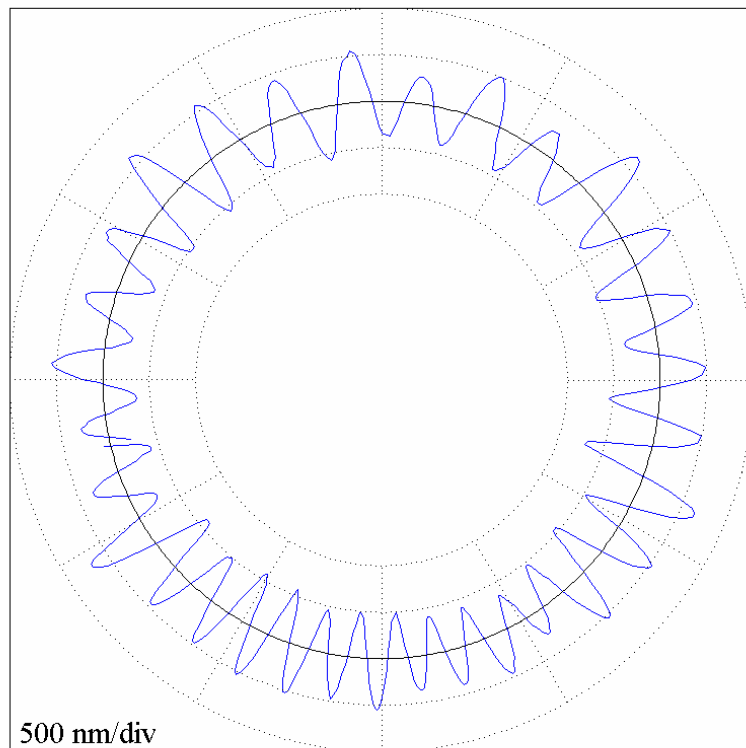


An Old Sensor a New Use



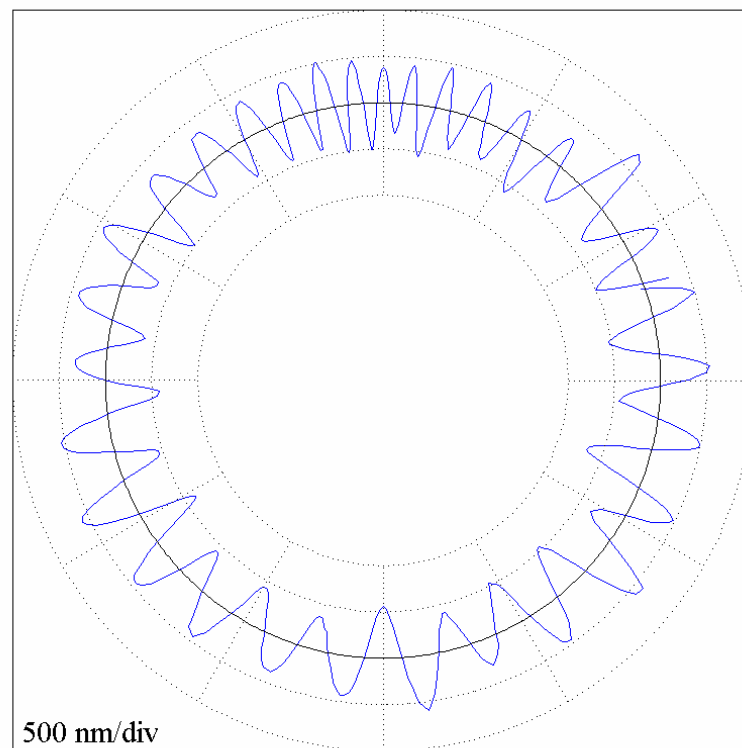
Real-Time Measurement

Probe 1



10 UPR High-Pass Filter

Probe 2

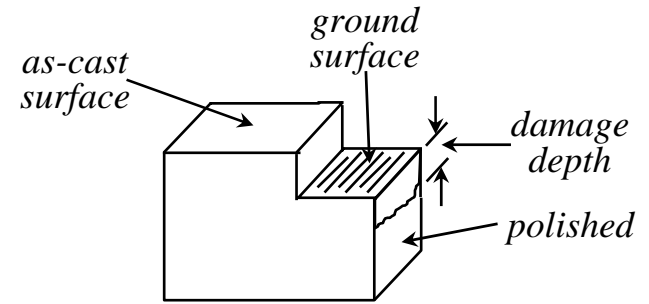
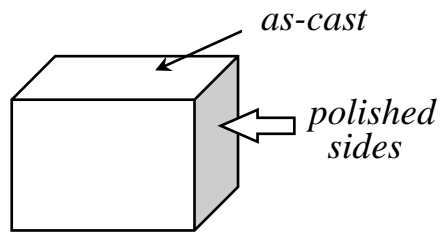


10 UPR High-Pass Filter

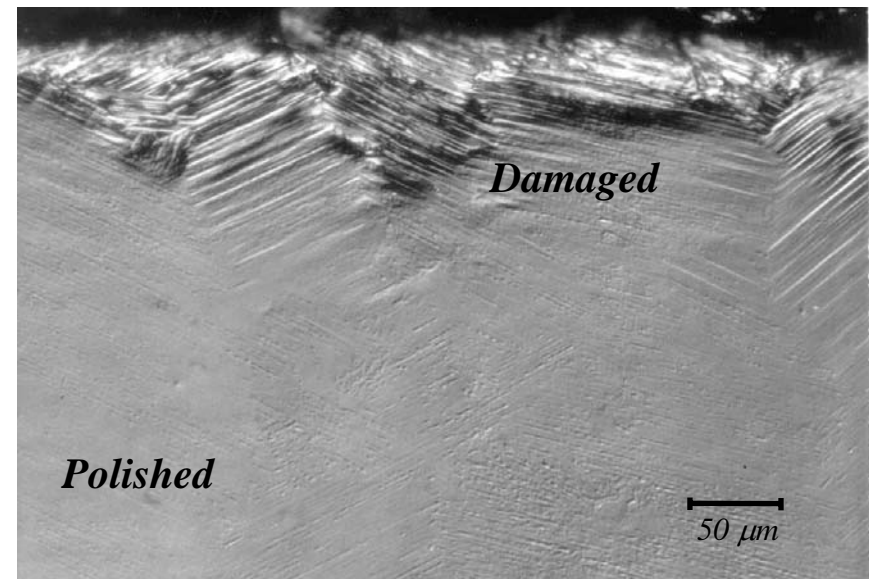
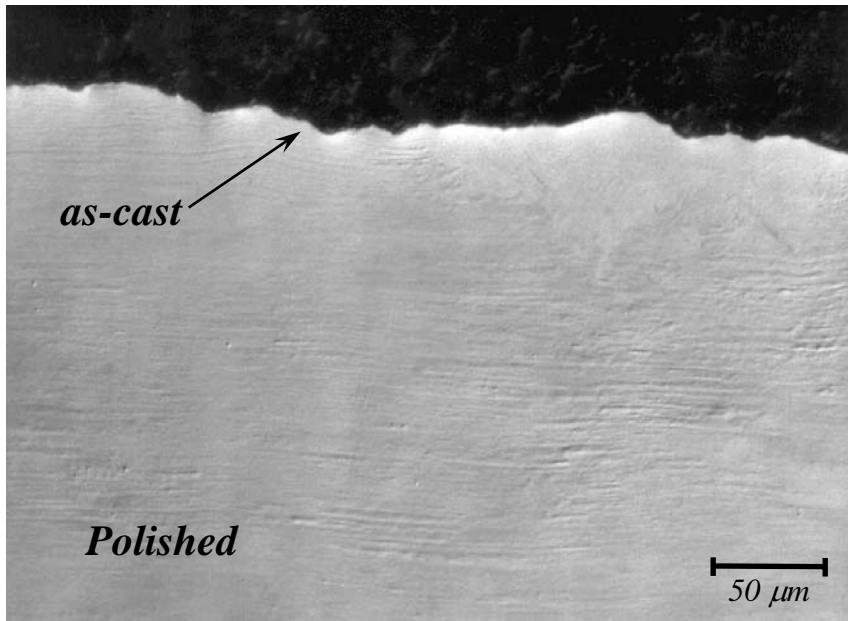
Redefining the Rules

- ❖ Open Architecture
 - Machine tools
 - Measurement systems
- ❖ Enhanced Metrology
 - 3-Dimensional
 - Real-Time interface
- ❖ Example: Turbine Blade Production
 - Process modeling
 - Process control
 - Metrology.

Subsurface Damage

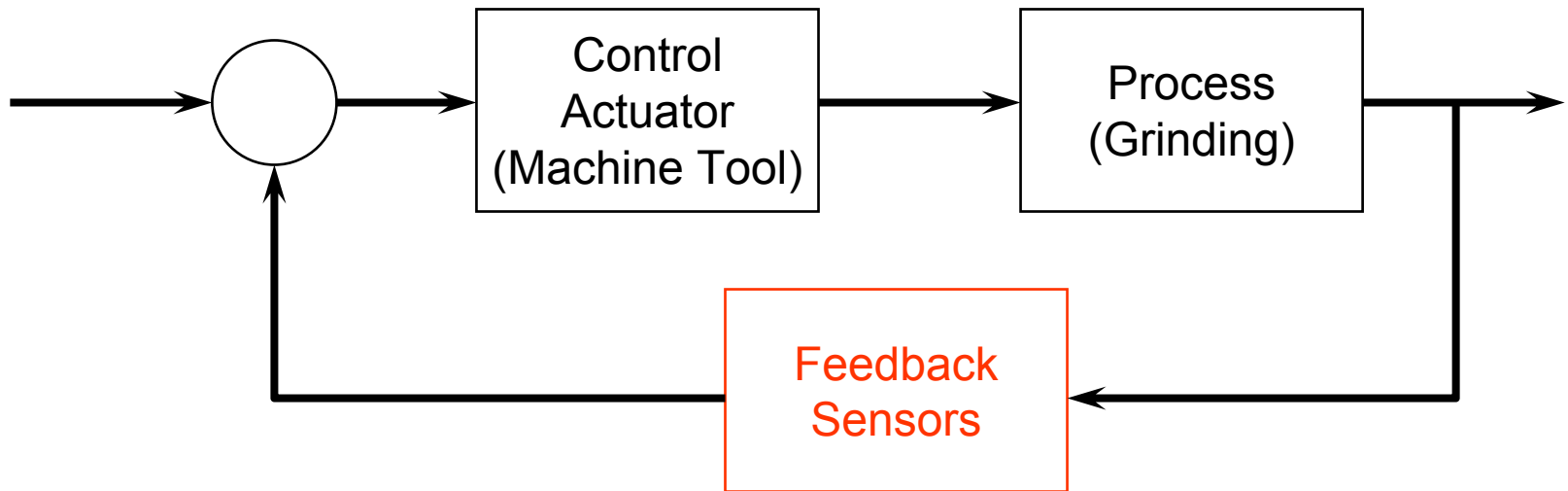


Ground Surface



$$V_s = 30 \text{ m/s}, V_w = 0.5 \text{ m/min}, a = 25 \text{ } \mu\text{m}$$

Manufacturing Process

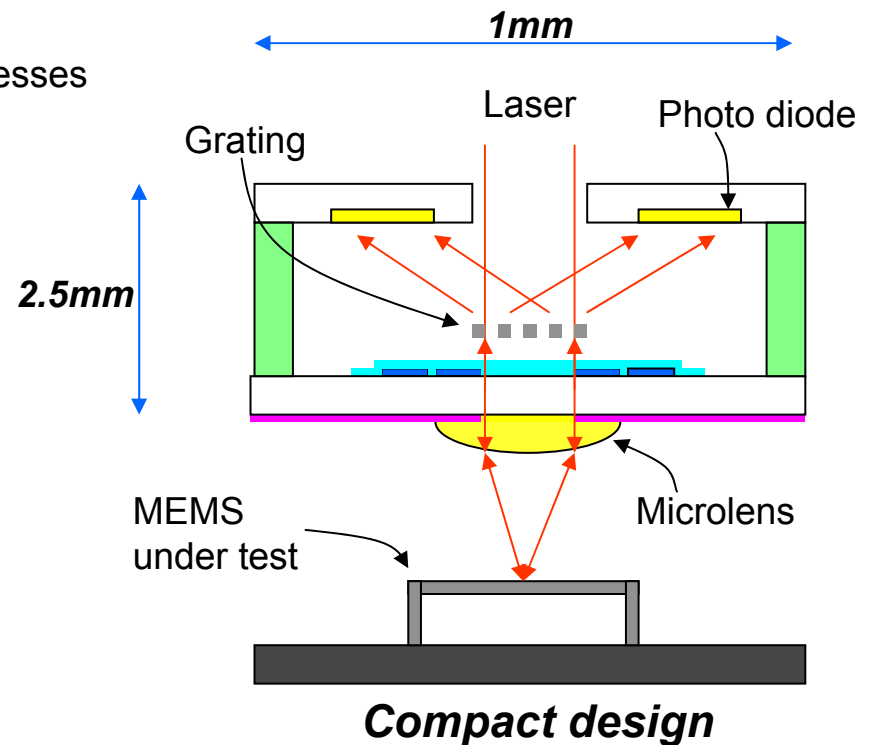
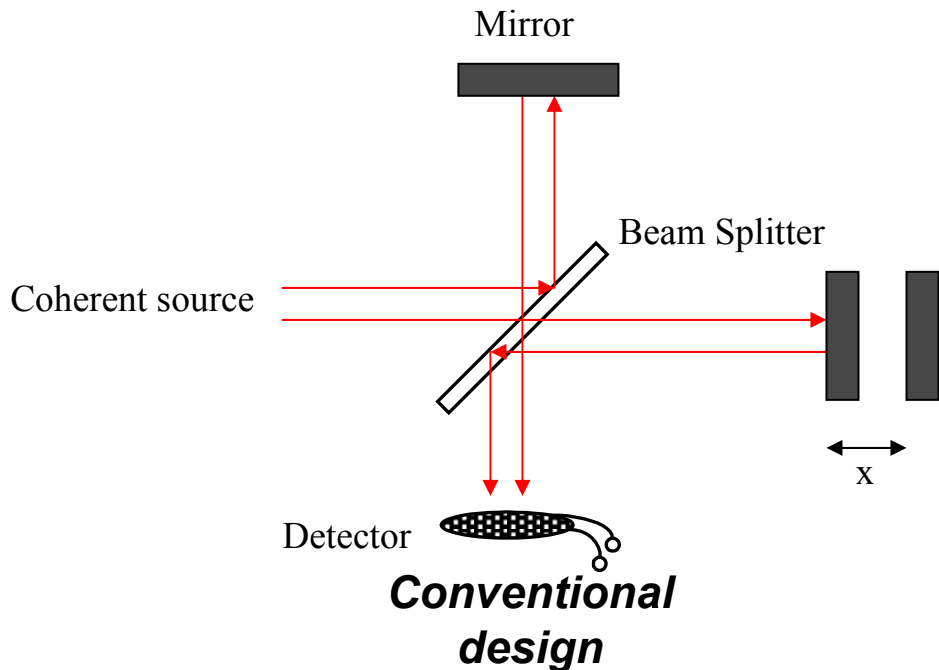


Small Sensors Satisfying Big Needs

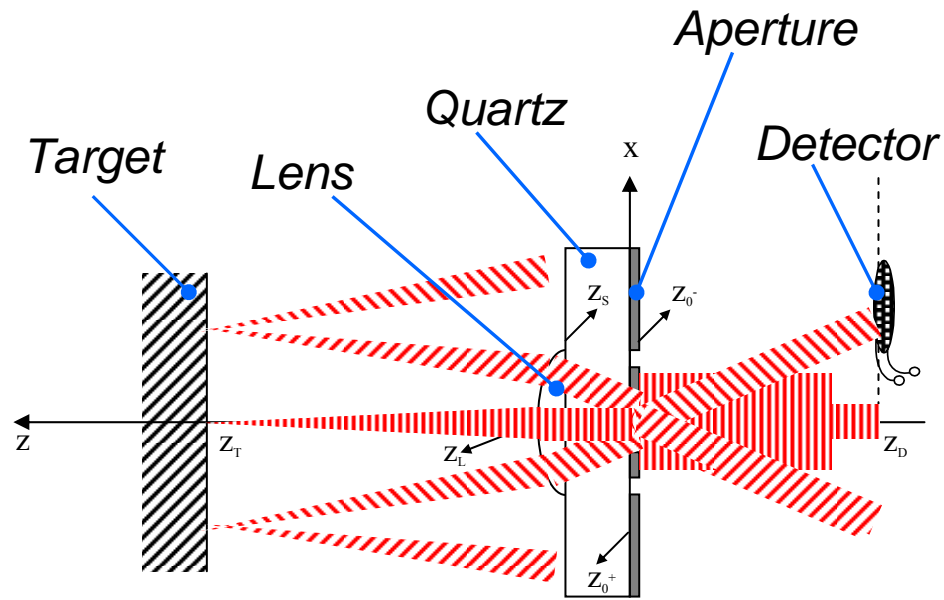
- ❖ High precision
- ❖ Fast
- ❖ Ability to analyze multiple devices
- ❖ Robust
- ❖ In-line and in-process
- ❖ Low cost
- ❖ Intelligent

New Compact Design - μ SGL

- ❖ **Compact design:** eliminating beam splitter, integration of electronics
 - Bulky \rightarrow small ($1 \times 1 \times 2.5 \text{ mm}^3$)
- ❖ Using a grating interferometer (Manalis *et al*, 1996)
 - Based on intensity measurement of the diffraction pattern
 - Displacement equivalent noise: $10^{-5} \text{ \AA}/\sqrt{\text{Hz}} \rightarrow$ resolution
- ❖ Better resolution at focus by microlens
- ❖ **Expensive \rightarrow Competitive**
 - proven microelectronics manufacturing processes



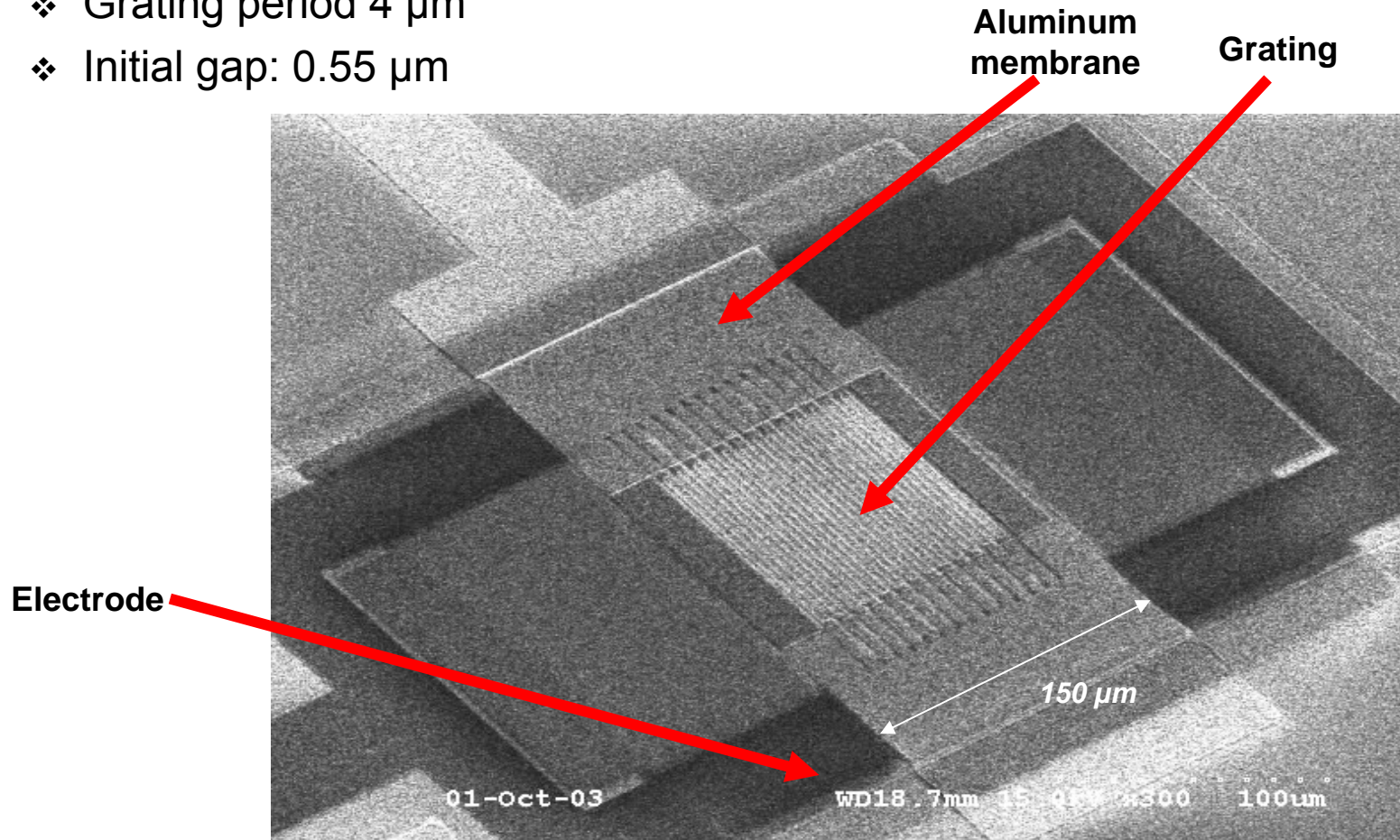
Detailed Beam Path



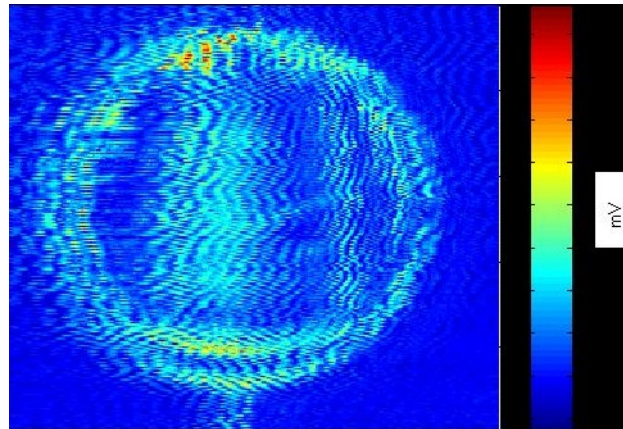
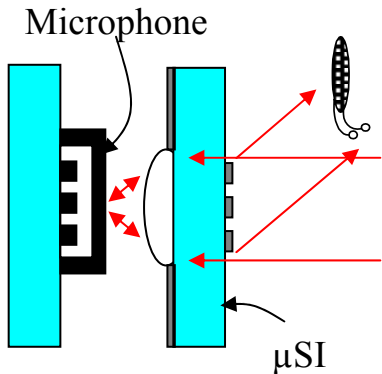
Coordinate system of analysis

SEM of Fabricated Micro-Interferometer

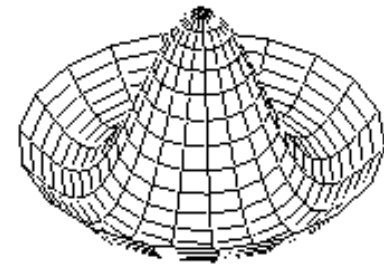
- ❖ Aluminum layer thickness: $1.8\ \mu\text{m}$ and $0.6\ \mu\text{m}$
- ❖ Grating period $4\ \mu\text{m}$
- ❖ Initial gap: $0.55\ \mu\text{m}$



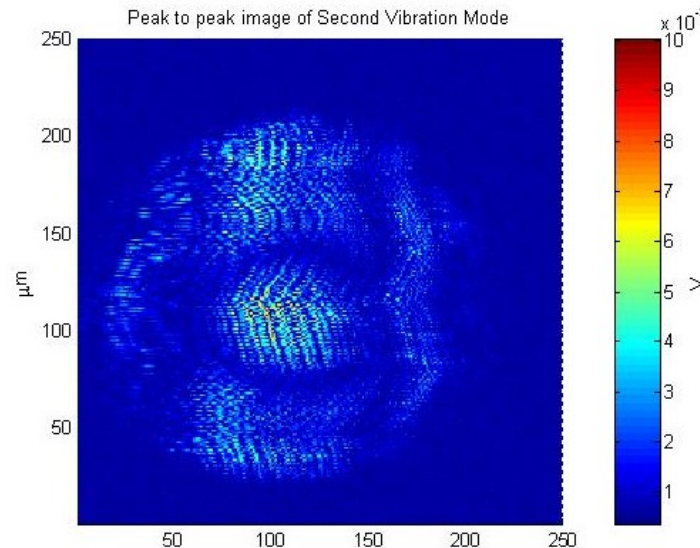
Improved Imaging Results-2nd Mode



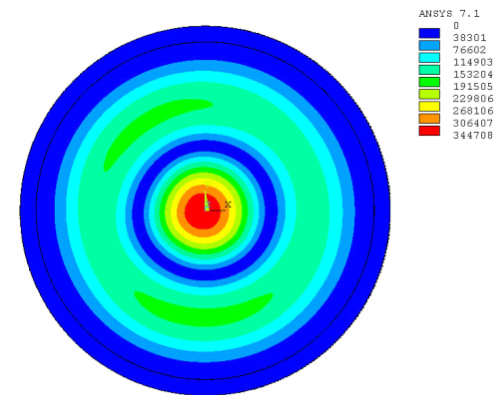
DC



- $\Phi 190\mu\text{m}$ microphone
- 2nd mode at 1.25MHz, DC 40V, AC 10V
- Vibration noise and fringes due to tilt & membrane curvature

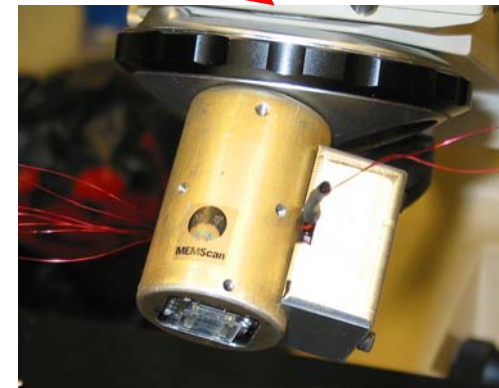
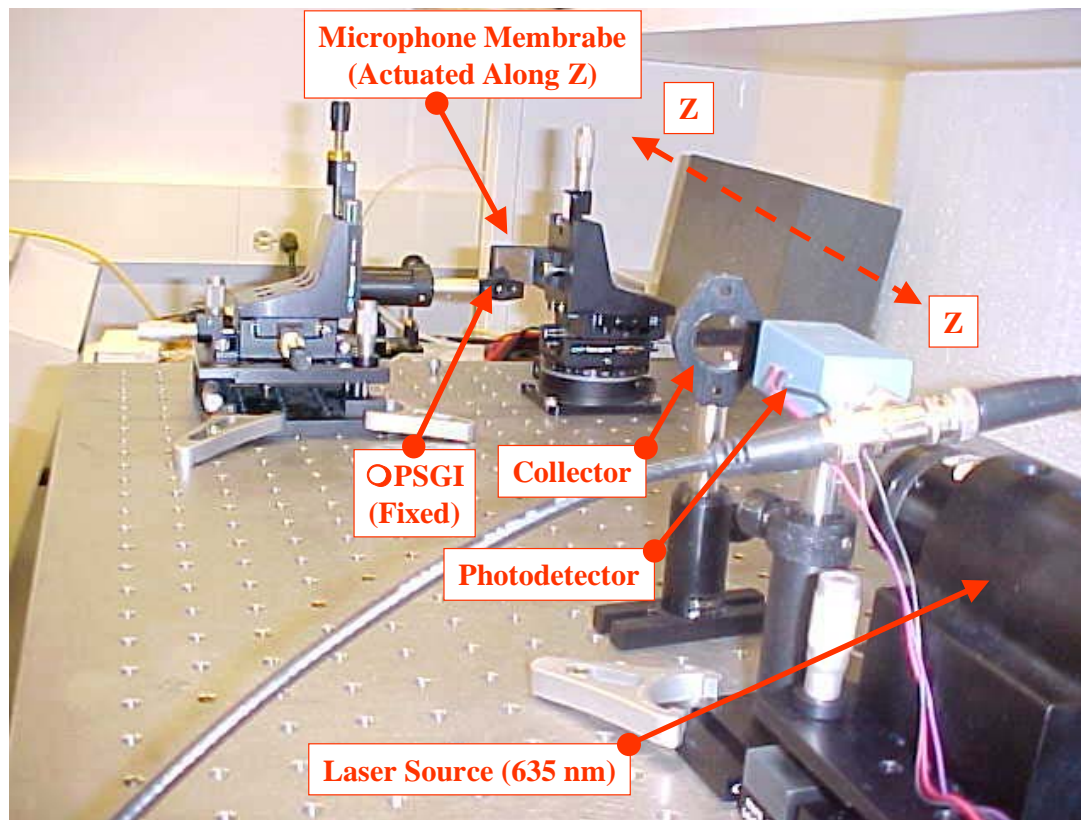


Motion at 2nd mode, AC



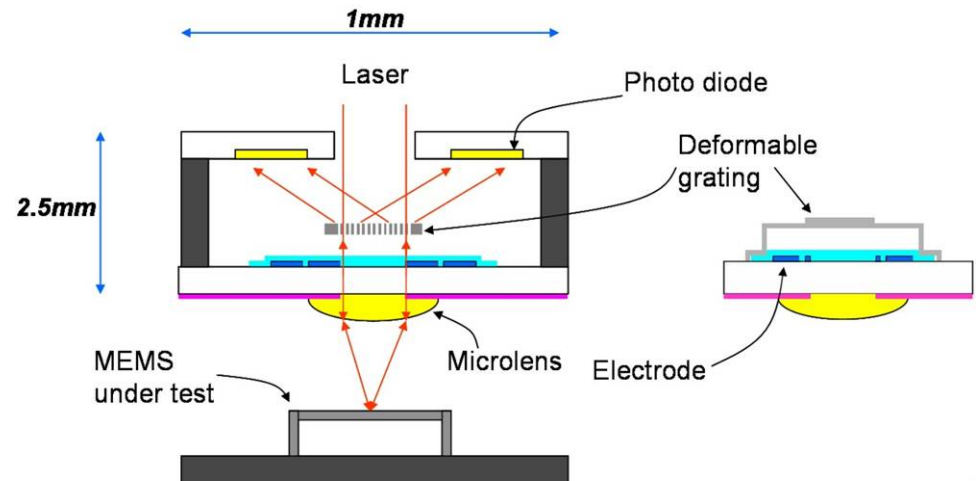
2nd mode in FEM

We Have Come Far!!!

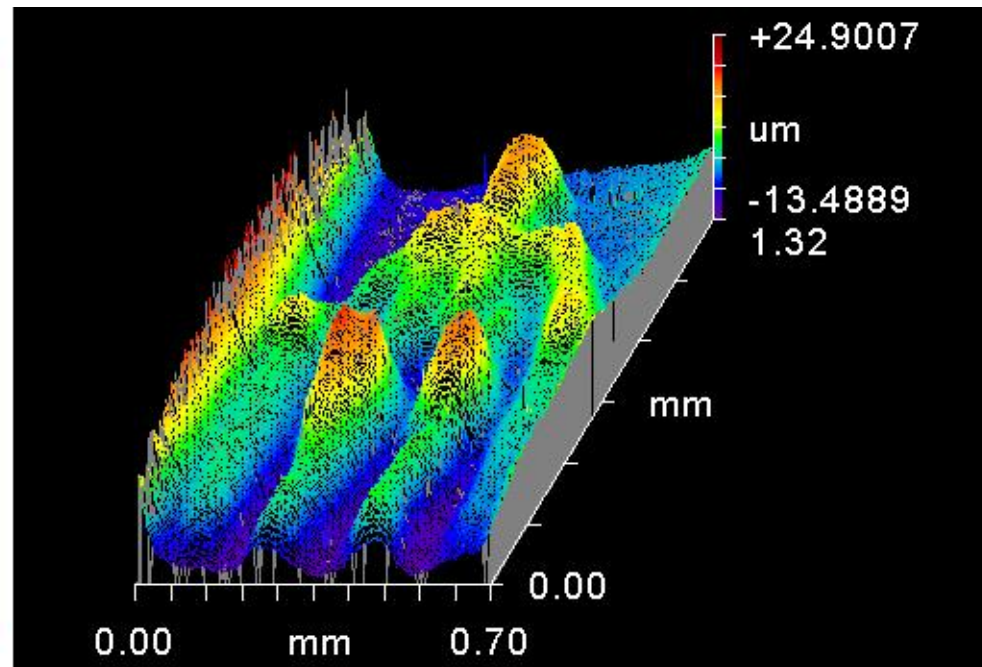
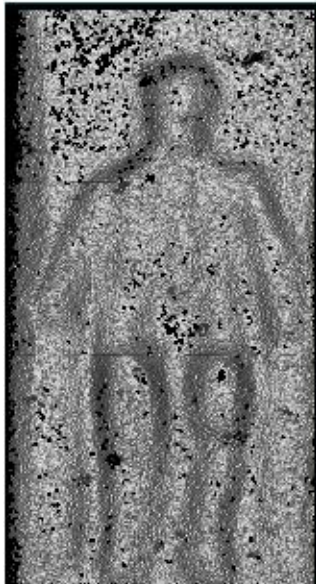


Technology Summary

- ❖ Emerging technology from Georgia Tech
- ❖ Based off of traditional laser interferometry, but on the micro scale
- ❖ Size 1mm x 1mm x 2.5mm
- ❖ Manufactured by standard silicon processing techniques
- ❖ Resolution:
 - Vertical: 0.5 nm
 - Lateral: 3.5 μm
- ❖ Potential to be produced in an array for fast inspection of entire wafers



Thinking Small Micro-Metrology - A Penny.



Another Direction - Thinking Big



Educational Issues

- ❖ Excellent Fundamental Problems
 - Undergraduate
 - Graduate
- ❖ Interdisciplinary
- ❖ Practical in Nature
- ❖ Real World Examples
- ❖ Basis for Professional Training

Conclusions

- ❖ Process Control is Viable
 - Classical parameters
 - New parameters
- ❖ Utility of Open Architecture Machines
- ❖ Real-Time adaptive control
 - Process parameter estimation
 - Integration of new sensors
- ❖ Next Generation Metrology
 - Real-Time
 - 3 D
 - Large Scale
 - Small Scale
- ❖ *We Can Do It All!*
 - Fundamental work
 - Industrial application
 - Education